



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DSC2G03

Silicon NPN epitaxial planar type

For high-frequency amplification

■ Features

- High transition frequency f_T
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: C6

■ Packaging

DSC2G03×0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CB0}	30	V
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Emitter-base voltage (Collector open)	V_{EBO}	3	V
Collector current	I_C	50	mA
Collector power dissipation	P_C	200	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Operating ambient temperature	T_{opr}	-40 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CB0}	$I_C = 100 \mu\text{A}, I_E = 0$	30			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 10 \mu\text{A}, I_C = 0$	3			V
Base-emitter voltage	V_{BE}	$V_{CE} = 10 \text{ V}, I_C = 2 \text{ mA}$		740		mV
Forward current transfer ratio	h_{FE}	$V_{CE} = 10 \text{ V}, I_C = 2 \text{ mA}$	25		250	—
Transition frequency ^{*1,2}	f_T	$V_{CE} = 10 \text{ V}, I_C = 15 \text{ mA}$	800		1 600	MHz
Reverse transfer capacitance (Common emitter)	C_{re}	$V_{CE} = 10 \text{ V}, I_C = 1 \text{ mA}, f = 10.7 \text{ MHz}$		0.9		pF
Reverse transfer capacitance (Common base)	C_{rb}	$V_{CB} = 6 \text{ V}, I_C = 0, f = 1 \text{ MHz}$		0.7		pF
Power gain	PG	$V_{CE} = 10 \text{ V}, I_C = 1 \text{ mA}, f = 200 \text{ MHz}$		20		dB

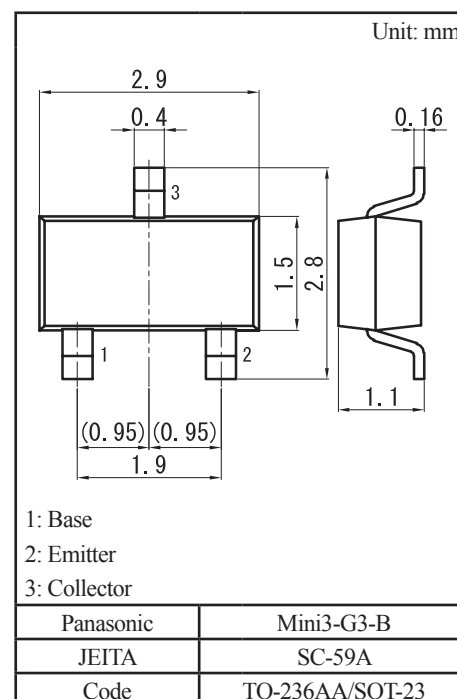
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

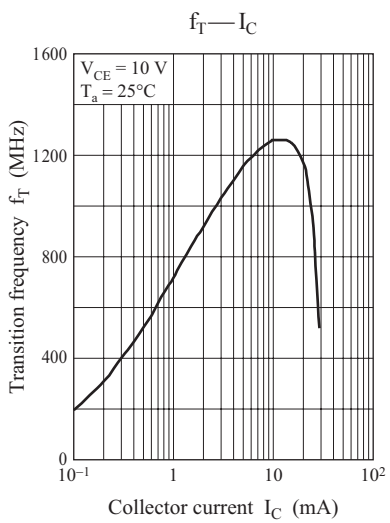
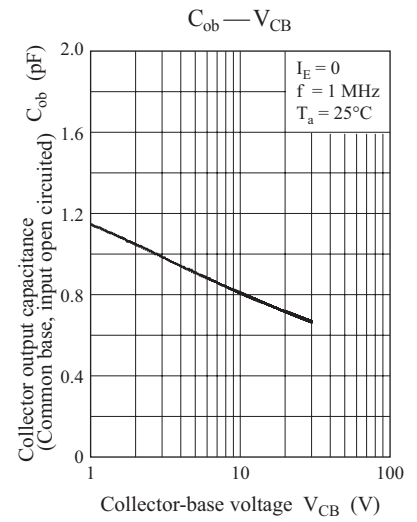
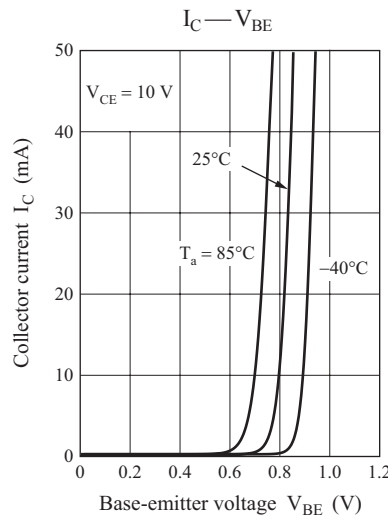
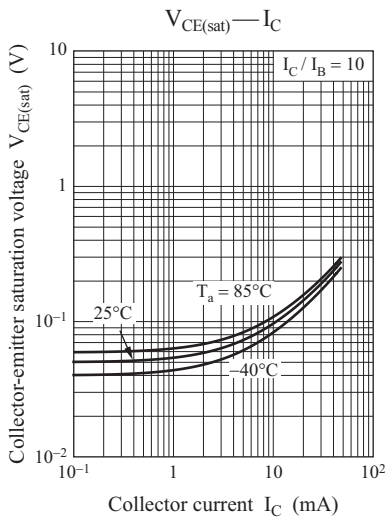
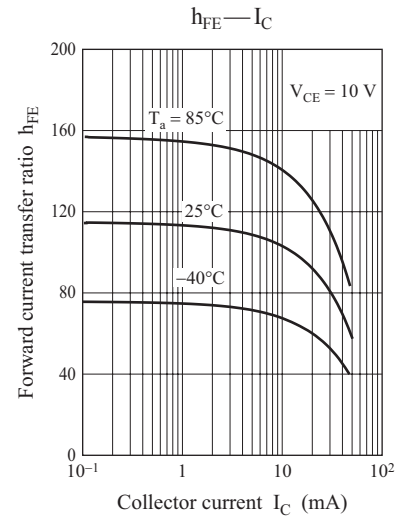
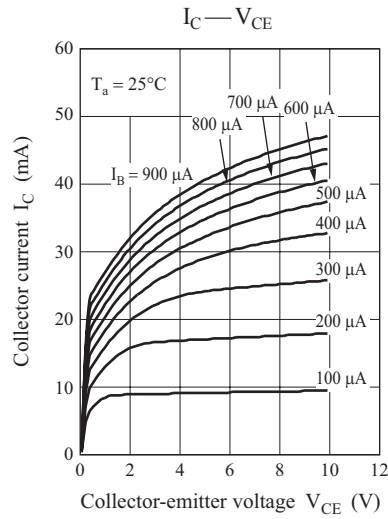
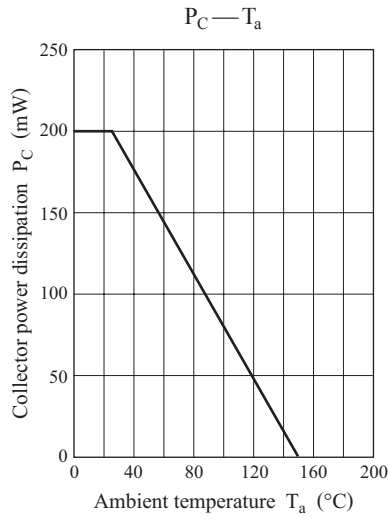
2. *1: Pulse measurement

*2: Rank classification

Code	T	S	0
Rank	T	S	No-rank
f_T	800 to 1400	1 000 to 1 600	800 to 1 600
Marking Symbol	C6T	C6S	C6

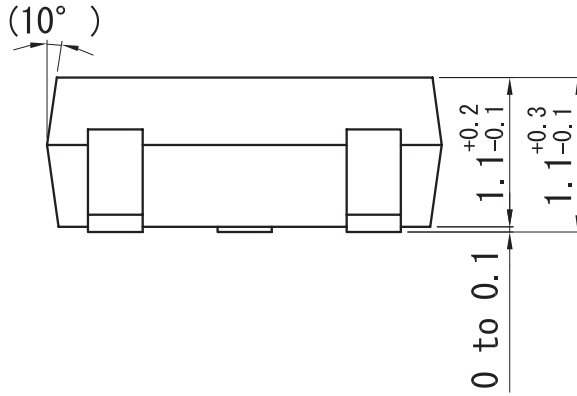
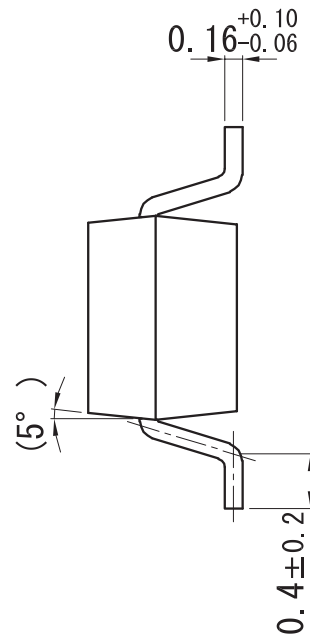
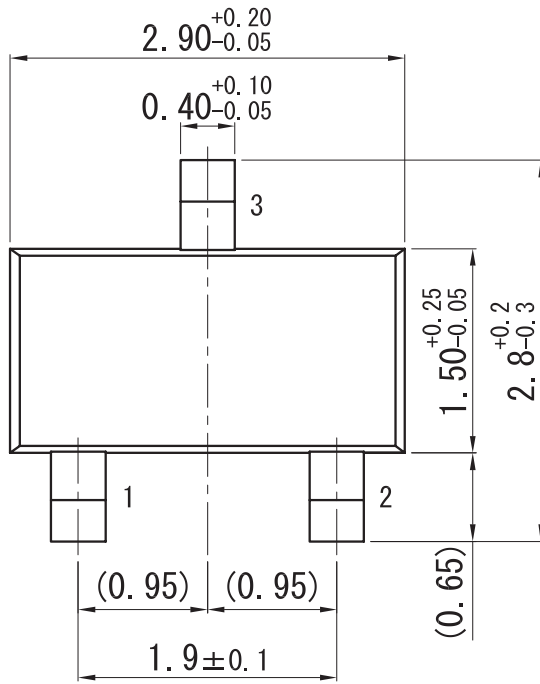
Product of no-rank is not classified and have no marking symbol for rank.



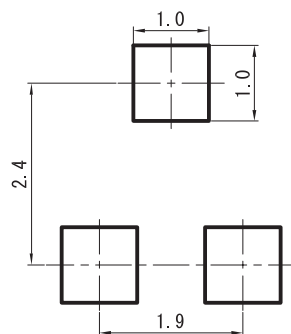


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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